Errata TMS320F2838x Real-Time MCUs Silicon Errata Silicon Revisions A, 0



ABSTRACT

This document describes the known exceptions to the functional specifications (advisories). This document may also contain usage notes. Usage notes describe situations where the device's behavior may not match presumed or documented behavior. This may include behaviors that affect device performance or functional correctness.

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1 Usage Notes and Advisories Matrices

Table 1-1 lists all usage notes and the applicable silicon revisions. Table 1-2 lists all advisories, modules affected, and the applicable silicon revisions.

1.1 Usage Notes Matrix

NUMBER	TITLE		SILICON REVISIONS AFFECTED	
		0	Α	
Section 3.1.1	PIE: Spurious Nested Interrupt After Back-to-Back PIEACK Write and Manual CPU Interrupt Mask Clear	Yes	Yes	
Section 3.1.2	Caution While Using Nested Interrupts	Yes	Yes	
Section 3.1.3	GPIO: GPIO Data Register is Reset by CPU1 Reset Only	Yes	Yes	
Section 3.1.4	McBSP: XRDY bit can Hold the Not-Ready-Status (0) if New Data is Written to the DX1 Register Without Verifying if the XRDY bit is in its Ready State (1)	Yes	Yes	
Section 3.1.5	Security: The primary layer of defense is securing the boundary of the chip, which begins with enabling JTAGLOCK and Zero-pin Boot to Flash feature	Yes	Yes	

Table 1-1. Usage Notes Matrix

1.2 Advisories Matrix

MODULE	DESCRIPTION	SILICON REVISIONS AFFECTED	
			A
ADC	ADC: External SOC Trigger (ADCEXTSOC) Cannot be Used to Trigger Multiple ADCs	Yes	No
ADC	ADC: DMA Read of Stale Result	Yes	Yes
ADC	ADC: Interrupts may Stop if INTxCONT (Continue-to-Interrupt Mode) is not Set	Yes	Yes
DCAN	During DCAN FIFO Mode, Received Messages May be Placed Out of Order in the FIFO Buffer	Yes	Yes
MCAN	Message Order Inversion When Transmitting From Dedicated Tx Buffers Configured With Same Message ID	Yes	Yes
EMAC	EMAC: Additional Words in Reception Buffer	Yes	Yes
EMAC	EMAC: Packet Filtering With TCP/UDP Filter (DNTU bit) Does not Work as Intended	Yes	Yes
ePWM	ePWM: An ePWM Glitch can Occur if a Trip Remains Active at the End of the Blanking Window	Yes	Yes
ePWM	ePWM: Trip Events Will Not be Filtered by the Blanking Window for the First 3 Cycles After the Start of a Blanking Window	Yes	Yes
ePWM	ePWM: Event Latch (DCxEVTxLAT) of "DC Event-Based CBC Trip" May not Extend Trigger Pulse as Expected When Asynchronous Path is Selected	Yes	No
ESC	ESC: EtherCAT Slave Controller Distributed Clocking (DC) Mode is not Supported	Yes	No
ESC	ESC: EtherCAT Slave Controller may not Work with a Non-Gigabit PHY	Yes	No
ESC	ESC: The CPU1 DMA Access is Only Available to the Lower 4KB of the ESC RAM Memory Map	Yes	No
Ethernet	Ethernet: MAC Receive VLAN Tag Hash Filter Always Operates in Default Mode	Yes	Yes
Ethernet	Ethernet: Assertion of Wrong Early Transmit Interrupt (ETI) for Context Descriptor	Yes	Yes
Ethernet	Ethernet: Incorrect Flexible Pulse-per-Second (PPS) Output Interval When Fine Correction Method is Used	Yes	No
Ethernet	Ethernet: False Dribble and CRC Error Reported in RMII 10Mbps Mode for a Specific Phase Relation Between MAC Receiver Clock and Assertion of RMII CRS_DV Input	Yes	No
FPU	FPU: FPU-to-CPU Register Move Operation Preceded by Any FPU 2p Operation	Yes	Yes
FSI	FSI: RX FIFO Spurious Overrun	Yes	No
GPIO	GPIO: Open-Drain Configuration may Drive a Short High Pulse	Yes	Yes
HWBIST	HWBIST: Avoiding Spurious Interrupts While Using HWBIST	Yes	Yes
HWBIST	HWBIST: No Cross-Triggering From One CPU While One of the C28x Cores is Going Through HWBIST Check	Yes	Yes
HWBIST	HWBIST: RTOSINT Interrupt Asserted During HWBIST Run Is Not Logged	Yes	Yes
I2C	I2C: Target Transmitter Mode, Standard Mode SDA Timings Limitation	Yes	Yes
INTOSC	INTOSC: VDDOSC Powered Without VDD can Cause INTOSC Frequency Drift	Yes	No
MCD	MCD: Missing Clock Detect Should be Disabled When the PLL is Enabled (PLLCLKEN = 1)	Yes	Yes
Memory	Memory: Prefetching Beyond Valid Memory	Yes	Yes

Table 1-2. Advisories Matrix

MODULE	DESCRIPTION		SILICON REVISIONS AFFECTED	
			A	
MPOST	MPOST: Memory Power-on-Self-Test will not Work at Full Speed	Yes	No	
Reset	Reset: Elevated VDD Current During Reset	Yes	No	
SDFM	SDFM: Dynamically Changing Threshold Settings (LLT, HLT), Filter Type, or COSR Settings Will Trigger Spurious Comparator Events	Yes	Yes	
SDFM	SDFM: Dynamically Changing Data Filter Settings (Such as Filter Type or DOSR) Will Trigger Spurious Data Acknowledge Events	Yes	Yes	
SDFM	SDFM: Two Back-to-Back Writes to SDCPARMx Register Bit Fields CEVT1SEL, CEVT2SEL, and HZEN Within Three SD-Modulator Clock Cycles can Corrupt SDFM State Machine, Resulting in Spurious Comparator Events	Yes	Yes	
SYSTEM	SYSTEM: Multiple Successive Writes to CLKSRCCTL1 Can Cause a System Hang	Yes	Yes	
USB	USB: USB DMA Event Triggers are not Supported	Yes	Yes	
Watchdog	Watchdog: WDKEY Register is not EALLOW-Protected	Yes	Yes	

Table 1-2. Advisories Matrix (continued)



2 Nomenclature, Package Symbolization, and Revision Identification 2.1 Device and Development-Support Tool Nomenclature

To designate the stages in the product development cycle, TI assigns prefixes to the part numbers of all DSP devices and support tools. Each DSP commercial family member has one of three prefixes: TMX, TMP, or TMS (for example, TMS320F28388D). Texas Instruments recommends two of three possible prefix designators for its support tools: TMDX and TMDS. These prefixes represent evolutionary stages of product development from engineering prototypes (TMX and TMDX) through fully qualified production devices and tools (TMS and TMDS).

Device development evolutionary flow:

- **TMX** Experimental device that is not necessarily representative of the final device's electrical specifications and may not use production assembly flow.
- **TMP** Prototype device that is not necessarily the final silicon die and may not necessarily meet final electrical specifications.
- TMS Production version of the silicon die that is fully qualified.

Support tool development evolutionary flow:

TMDX Development-support product that has not yet completed Texas Instruments internal qualification testing.

TMDS Fully-qualified development-support product.

TMX and TMP devices and TMDX development-support tools are shipped against the following disclaimer:

"Developmental product is intended for internal evaluation purposes."

Production devices and TMDS development-support tools have been characterized fully, and the quality and reliability of the device have been demonstrated fully. TI's standard warranty applies.

Predictions show that prototype devices (X or P) have a greater failure rate than the standard production devices. Texas Instruments recommends that these devices not be used in any production system because their expected end-use failure rate still is undefined. Only qualified production devices are to be used.

2.2 Devices Supported

This document supports the following devices:

- TMS320F28388D
- TMS320F28386D
- TMS320F28386D-Q1
- TMS320F28384D
- TMS320F28384D-Q1
- TMS320F28388S
- TMS320F28386S
- TMS320F28386S-Q1
- TMS320F28384S
- TMS320F28384S-Q1



2.3 Package Symbolization and Revision Identification

Figure 2-1 shows the package symbolization and Table 2-1 lists the silicon revision codes.

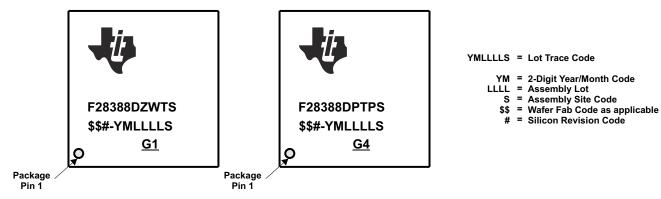


Figure 2-1. Package Symbolization

Table 2-1. Revision Identification			
SILICON REVISION CODE	SILICON REVISION	REVID ⁽¹⁾ Address: 0x5D00C	COMMENTS ⁽²⁾
Blank	0	0x0000 0000	This silicon revision is available as TMX.
A	А	0x0000 0001	This silicon revision is available as TMX and TMS.

(1) Silicon Revision ID

(2) For orderable device numbers, see the PACKAGING INFORMATION table in the TMS320F2838x Real-Time Microcontrollers With Connectivity Manager data sheet.



3 Silicon Revision A Usage Notes and Advisories

This section lists the usage notes and advisories for this silicon revision.

3.1 Silicon Revision A Usage Notes

This section lists all the usage notes that are applicable to silicon revision A [and earlier silicon revisions].

3.1.1 PIE: Spurious Nested Interrupt After Back-to-Back PIEACK Write and Manual CPU Interrupt Mask Clear

Revisions Affected: 0, A

Certain code sequences used for nested interrupts allow the CPU and PIE to enter an inconsistent state that can trigger an unwanted interrupt. The conditions required to enter this state are:

- 1. A PIEACK clear is followed immediately by a global interrupt enable (EINT or asm(" CLRC INTM")).
- 2. A nested interrupt clears one or more PIEIER bits for its group.

Whether the unwanted interrupt is triggered depends on the configuration and timing of the other interrupts in the system. This is expected to be a rare or nonexistent event in most applications. If it happens, the unwanted interrupt will be the first one in the nested interrupt's PIE group, and will be triggered after the nested interrupt reenables CPU interrupts (EINT or asm(" CLRC INTM")).

Workaround: Add a NOP between the PIEACK write and the CPU interrupt enable. Example code is shown below.

```
//Bad interrupt nesting code
PieCtrlRegs.PIEACK.all = 0xFFFF;
EINT;
//Enable nesting in the PIE
//Enable nesting in the CPU
//Good interrupt nesting code
PieCtrlRegs.PIEACK.all = 0xFFFF;
asm(" NOP");
EINT;
//Wait for PIEACK to exit the pipeline
//Enable nesting in the CPU
```

3.1.2 Caution While Using Nested Interrupts

Revisions Affected: 0, A

If the user is enabling interrupts using the EINT instruction inside an interrupt service routine (ISR) in order to use the nesting feature, then the user must disable the interrupts before exiting the ISR. Failing to do so may cause undefined behavior of CPU execution.

3.1.3 GPIO: GPIO Data Register is Reset by CPU1 Reset Only

Revisions Affected: 0, A

GPIO data registers are reset by CPU1 reset even though a GPIO pin is assigned to CPU2. This causes the GPIO pin to continue to drive the active value even when CPU2 is reset (by a reset source that only resets CPU2).

3.1.4 McBSP: XRDY bit can Hold the Not-Ready-Status (0) if New Data is Written to the DX1 Register Without Verifying if the XRDY bit is in its Ready State (1)

Revisions Affected: 0, A

If the XRDY bit is used to properly gate writes to the DX2/DX1 registers, this condition will not happen.

Per the operation of the McBSP, a write to the DX1 data transmit register will automatically clear the XRDY bit, indicating a not-ready-status. Once this data is transferred to the internal transmit shift register (XSR1), the McBSP HW will set the XRDY bit, indicating a ready-status, and new data can be written to DX2/DX1 data transmit registers.

If the set and clear of XRDY occur on the same CPU clock cycle, the XRDY bit will remain cleared and the new data in the DX2/DX1 will not be transmitted.

In this state of XRDY = 0, the McBSP will appear not-ready indefinitely.

Any subsequent writes to DX2/DX1 will behave normally and the XRDY bit will function as normal.

Workaround: When transmitting multiple words of data using the McBSP module, it is recommended that the XRDY bit in the SPCR2 register be polled before writing new data to the DX2/DX1 registers to prevent overwriting. For those modules that do not have access to the XRDY bit (such as the DMA controller), the XINT interrupt inside the McBSP module can be configured to reflect XRDY (via the XINTM bits in SPCR2 register); and this can also be used to gate writes to the DX2/DX1 registers. This will also ensure that the XRDY bit is not set and cleared on the same CPU cycle, causing the above "not-ready indefinitely" condition.

If the system allows multiple bus controllers (such as the C28x CPU and the DMA controller) to write to the DX2/DX1 registers, then the ready-state of the XRDY bit should be validated before passing control of the McBSP to a different bus controller. This will ensure that the state of XRDY is accurate and the simultaneous set/clear action does not occur.

3.1.5 Security: The primary layer of defense is securing the boundary of the chip, which begins with enabling JTAGLOCK and Zero-pin Boot to Flash feature

Revisions Affected: 0, A

Device security relies on the premise that unauthorized code is not allowed to enter the device and execute under any circumstances. To that end, the device provides two features that a user concerned about security should always enable.

JTAGLOCK

When enabled in the USER OTP area of flash, the JTAGLOCK feature disables JTAG access (for example, debugger connection) to resources on the device, blocking an unauthorized party from using the JTAG interface to download any code into the device. When JTAGLOCK is enabled, the user can still allow an authorized party to unlock it by entering a password, or they can lock it permanently by programming a password value of all all-zeros.

· Zero-pin Boot to Flash

The external bootloaders built into the TI ROM do not perform any authentication of the downloaded code. Enabling the Zero-pin boot option along with a flash boot mode in the USER OTP blocks all pin-based external bootloader options (for example, SCI, CAN, Parallel) from running at boot by forcing the boot process to jump immediately to internal flash after the base boot ROM execution concludes. For highest security, the Secure Flash boot mode can be chosen. This enables a pre-check of the flash code by the base boot ROM before jumping to it.

If JTAG is locked permanently and the Zero-pin Boot to Flash option is enabled, programming tools that communicate with the device through JTAG or the built-in bootloaders will not work. If the ability to perform firmware upgrades is desired, the user must pre-store code in flash to securely manage and perform the update.

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3.2 Silicon Revision A Advisories

This section lists all the advisories that are applicable to silicon revision A [and earlier silicon revisions].

Advisory	ADC: DMA Read of Stale Result
Revisions Affected	0, A
Details	 The ADCINT flag can be set before the ADCRESULT value is latched (see the t_{LAT} and t_{INT(LATE)} columns in the ADC Timings tables of the <i>TMS320F2838x Real-Time Microcontrollers With Connectivity Manager</i> data sheet). The DMA can read the ADCRESULT value as soon as 3 cycles after the ADCINT trigger is set. As a result, the DMA could read a prior ADCRESULT value when the user expects the latest result if all of the following are true: The ADC is in late interrupt mode. The ADC operates in a mode where t_{INT(LATE)} occurs 3 or more cycles before t_{LAT} (ADCCTL2 [PRESCALE] > 2 for 12-bit mode). The DMA is triggered from the ADCINT signal. The DMA is triggered sthe ADCRESULT value associated with that ADCINT signal without reading any other values first. The DMA reads listed above could result in reads of stale data; the following non-DMA methods will always read the expected data: The ADCINT flag triggers a CPU ISR. The CPU polls the ADCINT flag.
Workaround	Trigger two DMA channels from the ADCINT flag. The first channel acts as a dummy transaction. This will result in enough delay that the second channel will always read the

fresh ADC result.

Advisory	ADC: Interrupts may Stop if INTxCONT (Continue-to-Interrupt Mode) is not Set
Revisions Affected	0, A
Details	If ADCINTSELxNx[INTxCONT] = 0, then interrupts will stop when the ADCINTFLG is set and no additional ADC interrupts will occur. When an ADC interrupt occurs simultaneously with a software write of the ADCINTFLGCLR register, the ADCINTFLG will unexpectedly remain set, blocking future ADC interrupts.
Workarounds	 Use Continue-to-Interrupt Mode to prevent the ADCINTFLG from blocking additional ADC interrupts: <pre>ADCINTSEL1N2[INTICONT] = 1; ADCINTSEL1N2[INTICONT] = 1; ADCINTSEL3N4[INT3CONT] = 1; ADCINTSEL3N4[INT4CONT] = 1;</pre> Ensure there is always sufficient time to service the ADC ISR and clear the ADCINTFLG before the next ADC interrupt occurs to avoid this condition. Check for an overflow condition in the ISR when clearing the ADCINTFLG. Check ADCINTOVF immediately after writing to ADCINTFLGCLR; if it is set, then write ADCINTFLGCLR a second time to ensure the ADCINTFLG is cleared. The ADCINTOVF register will be set, indicating an ADC conversion interrupt was lost. AdcaRegs.ADCINTFLGCLR.bit.ADCINT1 = 1; //clear INT1 flag if(1 == AdcaRegs.ADCINTOVF.bit.ADCINT1 = 1; //clear INT1 again // If the ADCINTOVF condition will be ignored by the application // then clear the flag here by writing 1 to ADCINTOVFCLR. // If there is a ADCINTOVF handling routine, then either insert // that code and clear the ADCINTOVF flag here or do not clear // the ADCINTOVF here so the external routine will detect the // condition. // AdcaRegs.ADCINTOVFCLR.bit.ADCINT1 = 1; // clear OVF



Advisory	During DCAN FIFO Mode, Received Messages May be Placed Out of Order in the FIFO Buffer
Revisions Affected	0, A
Details	In DCAN FIFO mode, received messages with the same arbitration and mask IDs are supposed to be placed in the FIFO in the order in which they are received. The CPU then retrieves the received messages from the FIFO via the IF1/IF2 interface registers. Some messages may be placed in the FIFO out of the order in which they were received. If the order of the messages is critical to the application for processing, then this behavior will prevent the proper use of the DCAN FIFO mode.
Workaround	Use the DMA to read out the FIFO via the IF3 register. Each time a message is received into the FIFO, the data is also copied to the IF3 register, and a DMA request Is generated to the DMA module to read out the data.

Advisory	Message Order Inversion When Transmitting From Dedicated Tx Buffers Configured With Same Message ID
Revisions Affected	0, A
Details	Multiple Tx Buffers are configured with the same Message ID. Transmission of these Tx buffers is requested sequentially in ascending order with a delay between the individual Tx requests. Depending on the delay between the individual Tx requests, the Tx Buffers may not be transmitted in the expected ascending order of the Tx Buffer number.
Workaround	First, write the group of Tx messages with same Message ID to the Message RAM. Then, request transmission of all of these messages concurrently by a single write access to TXBAR .
	Use the Tx FIFO instead of dedicated Tx Buffers for the transmission of several messages with the same Message ID in a specific order.



Advisory	EMAC: Additional Words in Reception Buffer
Revisions Affected	0, A
Details	If the DMA burst size is not aligned with the EMAC packet size, then additional words are observed in the reception buffer. This can cause overriding of the variables immediately after the reception buffer.
	For example:
	 If the packet length is 68 bytes, two additional words of 32 bits will be received in the reception buffer. The expected length is 72 bytes (68 bytes of data + FCS). If the packet size is 72 bytes, one additional word of 32 bits will be received in the reception buffer. The expected length is 76 bytes (72 bytes +FCS).
Workaround	Set the burst length to 1 by configuring the "RXPBL" field of the Dma_Chx_Rx_Control register to 1, or have a wider buffer than necessary to avoid unwanted data corruption.
Advisory	EMAC: Packet Filtering With TCP/UDP Filter (DNTU bit) Does not Work as Intended
Revisions Affected	0, A
Details	
	The DNTU bit of the MAC_Packet_Filter register is expected to drop the non-TCP or UDP-over-IP packets. The MAC forwards only those packets that are processed by the Layer 4 filter.
	This functionality is not working and the EMAC is not dropping these packets even if this bit is set.
Workaround	None

www.ti.com	Silicon Revision A Usage Notes and Advisories
Advisory	ePWM: An ePWM Glitch can Occur if a Trip Remains Active at the End of the Blanking Window
Revisions Affected	0, A
Details	The blanking window is typically used to mask any PWM trip events during transitions which would be false trips to the system. If an ePWM trip event remains active for less than three ePWM clocks after the end of the blanking window cycles, there can be an undesired glitch at the ePWM output.
	Figure 3-1 illustrates the time period which could result in an undesired ePWM output.
	3 ePWM cycles Blanking Window Active Blanking Complete Trip Source Trip Active Undesired Trip Active-to-Inactive Transition
	Figure 3-1. Undesired Trip Event and Blanking Window Expiration
	Figure 3-2 illustrates the two potential ePWM outputs possible if the trip event ends within 1 cycle before or 3 cycles after the blanking window closes.
	ePWM Output Pin (Possibility A) (Trip interrupt will be issued) Active State Trip State Trip State
	ePWM Output Pin (Possibility B) (Trip interrupt will not be issued) Active State Active State
	Figure 3-2. Resulting Undesired ePWM Outputs Possible
Workaround	Extend or reduce the blanking window to avoid any undesired trip action.
Advisory	ePWM: Trip Events Will Not be Filtered by the Blanking Window for the First 3 Cycles After the Start of a Blanking Window
Revisions Affected	0, A
Details	The Blanking Window will not blank trip events for the first 3 cycles after the start of a Blanking Window. DCEVTFILT may continue to reflect changes in the DCxEVTy signals. If DCEVTFILT is enabled, this may impact subsequent subsystems that are configured (for example, the Trip Zone submodule, TZ interrupts, ADC SOC, or the PWM output).
Workaround	Start the Blanking Window 3 cycles before blanking is required. If a Blanking Window is needed at a period boundary, start the Blanking Window 3 cycles before the beginning of the next period. This works because Blanking Windows persist across period boundaries.



Advisory	Ethernet: MAC Receive VLAN Tag Hash Filter Always Operates in Default Mode								
Revisions Affected	0, A								
Details	The ETV, DOVLTC, and ERSVLM bits of the MAC_VLAN_Tag_Data register accessed via the MAC_VLAN_Tag_Ctrl register (Extended Receive VLAN filtering is selected) are used to program the mode of operation of the Receive VLAN Hash Filtering. The ETV bit is used to enable computation of Hash for only 12 bits of VLAN Tag. The DOVLTC bit is used to disable VLAN Type Check for VLAN Hash filtering. The ERSVLM bit is used to enable VLAN Hash filtering for S-VLAN Type. However, due to this defect, the Receive VLAN Hash filter always operates in default mode; that is, VLAN Hash is always computed for 16-bits (ETV = 0) of C-VLAN Tag (DOVLTC = 0 and ERSVLM = 0). Therefore, programming the ETV, DOVLTC, or ERSVLM bits to 1 has no effect because these bits have an incorrect read-only attribute. As a result, unintended packets might be forwarded to the application due to an incorrect filter pass or bypass results/status. Also, packets might be dropped in the MAC due to an incorrect filter fail result.								
	The defect is applicable when non-default VLAN Hash filtering modes are programmed; that is, one or more of the ETV, DOVLTC, and ERSVLM bits are set to 1.								
Workaround	The software should disable the Receive VLAN Hash filtering by setting the VTHM bit of the MAC_VLAN_Tag_Ctrl register to 0 (when non-default VLAN Hash filtering mode is required) and use the alternative filtering methods available in the hardware (perfect or inverse VLAN filtering), or perform filtering in software.								
	Use only the default VLAN Hash filtering modes.								
Advisory	Ethernet: Assertion of Wrong Early Transmit Interrupt (ETI) for Context Descriptor								
Revisions Affected	0, A								
Details	When the ETIC bit is set in the DMA_CHx_TX_Control register, and if the DMA Transmit Ring contains the Transmit Context descriptor, the DMA engine wrongly asserts the ETI through the SBD_Interrupt.								
Workaround	While processing the ring in the interrupt handling code, if the Context Descriptor is found queued, skip the descriptor. Check if the CTXT bit of the TDES3 Descriptor was set, then ignore the packet. The interrupt should not be used for Transmit buffer handling.								

Advisory	FPU: FPU-to-CPU Register Move Operation Preceded by Any FPU 2p Operation								
Revisions Affected	0, A								
Details	This advisory applies when a multicycle (2p) FPU instruction is followed by a FPU-to-CPU register transfer. If the FPU-to-CPU read instruction source register is the same as the 2p instruction destination, then the read may be of the value of the FPU register before the 2p instruction completes. This occurs because the 2p instructions rely on data-forwarding of the result during the E3 phase of the pipeline. If a pipeline stall happens to occur in the E3 phase, the result does not get forwarded in time for the read instruction.								
	The 2p instructions impacted by this advisory are MPYF32, ADDF32, SUBF32, and MACF32. The destination of the FPU register read must be a CPU register (ACC, P, T, XAR0XAR7). This advisory does not apply if the register read is a FPU-to-FPU register transfer.								
	In the example below, the 2p instruction, MPYF32, uses R6H as its destination. The FPU register read, MOV32, uses the same register, R6H, as its source, and a CPU register as the destination. If a stall occurs in the E3 pipeline phase, then MOV32 will read the value of R6H before the MPYF32 instruction completes.								

Example of Problem:

MPYF32 R6H, R5H, R0H	; 2p FPU instruction that writes to R6H
F32TOUI16R R3H, R4H ADDF32 R2H, R2H, R0H	; delay slot
MOV32 *SP, R2H MOV32 @XAR3, R6H	; alignment cycle ; FPU register read of R6H

Figure 3-3 shows the pipeline diagram of the issue when there are no stalls in the pipeline.

	Instruction	F1	F2	D1	D2	R1	R2	E	w		Comments
		I	FPU pipeline>		R1	R2	E1	E2	E3	Comments	
Il	MPYF32 R6H, R5H, R0H MOV32 *XAR7++, R4H	Il									
I2	F32TOUI16R R3H, R4H	I2	I1								
I3	ADDF32 R3H, R2H, R0H MOV32 *SP, R2H	I3	I2	Il							
I4	MOV32 @XAR3, R6H	I4	I3	I2	I1						
			I4	13	I2	I1					
				I4	I3	I2	I1				
					I4	I3	I2	I1			
						I4	I3	I2	I1		
							<u>14</u>	13	I2	т1	14 samples the result as it enters the R2 phase. The product R6H=R5H*R0H (II) finishes computing in the E3 phase, but is forwarded as an operand to I4. This makes I4 appear to be a 2p instruction, but I4 actually takes 3p cycles to compute.
								I4	I3	I2	
									I4	I3	

Figure 3-3. Pipeline Diagram of the Issue When There are no Stalls in the Pipeline



Advisory (continued) FPU: FPU-to-CPU Register Move Operation Preceded by Any FPU 2p Operation

Figure 3-4 shows the pipeline diagram of the issue if there is a stall in the E3 slot of the instruction I1.

	Instruction	F1	F2	D1	D2	R1	R2	E	w		
		FPU pipeline			>	R1	R2	E1	E2	E3	Comments
Il	MPYF32 R6H, R5H, R0H MOV32 *XAR7++, R4H	Il									
I2	F32TOUI16R R3H, R4H	I2	I1								
I3	ADDF32 R3H, R2H, R0H MOV32 *SP, R2H	I3	I2	Il							
I4	MOV32 @XAR3, R6H	I4	I3	I2	I1						
			I4	I3	I2	I1					
				I4	I3	I2	I1				
					I4	I3	I2	I1			
						I4	I3	I2	I1		
							<u>14</u>	I3	I2	I1 (STALL)	14 samples the result as it enters the R2 phase, but I1 is stalled in E3 and is unable to forward the product of R5H*R0H to I4 (R6H does not have the product yet due to a design bug). So, I4 reads the old value of R6H.
							I4	I3	I2	Il	There is no change in the pipeline as it was stalled in the previous cycle. I4 had already sampled the old value of R6H in the previous cycle.
								Ι4	IЗ	I2	Stall over

Figure 3-4. Pipeline Diagram of the Issue if There is a Stall in the E3 Slot of the Instruction I1

Workaround

Treat MPYF32, ADDF32, SUBF32, and MACF32 in this scenario as 3p-cycle instructions. Three NOPs or non-conflicting instructions must be placed in the delay slot of the instruction.

The C28x Code Generation Tools v.6.2.0 and later will both generate the correct instruction sequence and detect the error in assembly code. In previous versions, v6.0.5 (for the 6.0.x branch) and v.6.1.2 (for the 6.1.x branch), the compiler will generate the correct instruction sequence but the assembler will not detect the error in assembly code.

Example of Workaround:

MPYF32 R6H, R5H, R0H MOV32 *XAR7++, R4H F32TOUI16R R3H, R4H ADDF32 R2H, R2H, R0H	; 3p FPU instruction that writes to R6H ; delay slot
MOV32 *SP, R2H	; delay slot
NOP	; alignment cycle
MOV32 @XAR3, R6H	; FPU register read of R6H

Figure 3-5 shows the pipeline diagram with the workaround in place.

Advisory (continued) FPU: FPU-to-CPU Register Move Operation Preceded by Any FPU 2p Operation

	Instruction	F1	F2	D1	D2	R1	R2	E	w		_	
		FPU pipelir		eline> R1		R1	R2	E1	E2	E3	Comments	
Il	MPYF32 R6H, R5H, R0H MOV32 *XAR7++, R4H	I1										
I2	F32TOUI16R R3H, R4H	I2	I1									
I3	ADDF32 R3H, R2H, R0H MOV32 *SP, R2H	I3	I2	Il								
I4	NOP	I4	I3	I2	I1							
15	MOV32 @XAR3, R6H	I5	I4	I3	I2	I1						
			I5	I4	I3	I2	I1					
				I5	I4	I3	I2	I1				
					I5	I4	I3	I2	I1			
						I5	I4	I3	I2	I1 (STALL)	Due to one extra NOP, I5 does not reach R2 when I1 enters E3; thus, forwarding is not needed.	
						I5	I4	I3	I2	Il	There is no change due to the stall in the previous cycle.	
							15	I4	13	12	Il moves out of E3 and I5 moves to R2. R6H has the result of R5H*R0H and is read by I5. There is no need to forward the result in this case.	
							_	I5	I4	I3		

Figure 3-5. Pipeline Diagram With Workaround in Place



Advisory	GPIO: Open-Drain Configuration may Drive a Short High Pulse
Revisions Affected	0, A
Details	Each GPIO can be configured to an open-drain mode using the GPxODR register. However, an internal device timing issue may cause the GPIO to drive a logic-high for up to 0–10 ns during the transition into or out of the high-impedance state.
	This undesired high-level may cause the GPIO to be in contention with another open- drain driver on the line if the other driver is simultaneously driving low. The contention is undesirable because it applies stress to both devices and results in a brief intermediate voltage level on the signal. This intermediate voltage level may be incorrectly interpreted as a high level if there is not sufficient logic-filtering present in the receiver logic to filter this brief pulse.
Workaround	<pre>If contention is a concern, do not use the open-drain functionality of the GPIOs; instead, emulate open-drain mode in software. Open-drain emulation can be achieved by setting the GPIO data (GPxDAT) to a static 0 and toggling the GPIO direction bit (GPxDIR) to enable and disable the drive low. For an example implementation, see the code below.</pre> <pre>void main(void) { // GPIO configuration EALLOW; GpioCtrlRegs.GPxPUD.bit.GPIOx = 1; // disable pullup GpioCtrlRegs.GPxODR.bit.GPIOx = 0; // set GPIO to drive static 0 before GpioDataRegs.GPxCLEAR.bit.GPIOx = 1; EDIS; // application code // To drive 0, set GPIO direction as output GpioCtrlRegs.GPxDIR.bit.GPIOx = 1; // To tri-state the GPIO(logic 1), set GPIO as input GpioCtrlRegs.GPxDIR.bit.GPIOx = 0; }</pre>

Advisory	HWBIST: Avoiding Spurious Interrupts While Using HWBIST
Revisions Affected	0, A
Details	HWBIST has the capability to log interrupts received while the CPU is under test and reissue them after HWBIST completes. Interrupts received in the clock cycle before the interrupt logging is enabled are executed before the HWBIST runs. In the next cycle, when interrupt logging is enabled, interrupts are logged and reissued when the HWBIST completes.
	The interrupt events for CPU Timer 1 and CPU Timer 2 are valid for 2 SYSCLK cycles. If the first cycle happens a cycle before interrupt logging is enabled and the second cycle coincides with the enabling of interrupt logging, the interrupt is executed once as expected before the logging (clearing the CPU Timer TCR.TIF flag), but then is logged by the interrupt logger and triggered again after HWBIST completes. Because the TCR.TIF flag was already cleared by the previous ISR, this is an unexpected spurious interrupt.
	This is only applicable to the non-PIE CPU Timer interrupts. The CPU Timer 0 interrupt is managed by the PIE and its pulse width is only one SYSCLK cycle.
Workarounds	 Disable CPU Timer 1 and 2 interrupts before enabling interrupt logging and restore them later. The steps are: Clear the timer interrupt enable bit TCR.TIE for CPU Timers 1 and 2. Run normal HWBIST sequence: save registers, enable interrupt logging, run HWBIST, restore registers, end interrupt logging. Check if the CPU Timers' TCR.TIF flags are set. If the flags are set, set the corresponding CPU IFR bit to trigger the interrupt. Restore TCR.TIE.
Advisory	HWBIST: No Cross-Triggering From One CPU While One of the C28x Cores is Going Through HWBIST Check
Revisions Affected	0, A
Details	While HWBIST check is ongoing on one of the C28x cores, any cross-trigger events from other CPUs (second C28x core or CM) can cause the HWBIST check to fail. This is due to the fact that cross-trigger input is missing an input isolation during HWBIST.
Workaround	No cross-triggering should be done while HWBIST is active.



Advisory	HWBIST: RTOSINT Interrupt Asserted During HWBIST Run Does Not Get Logged
Revisions Affected	0, A
Details	During HWBIST, all valid interrupt sources except ERAD are logged. The application can read the ERAD System Event Interrupt status flags after HWBIST completion to check for any pending interrupts. This check is necessary only if the application uses ERAD functionalities.
Workaround	 When RTOSINT from ERAD is enabled, the interrupt generated during HWBIST execution will not be latched inside the CPU. The application should perform the following sequence of operations (before/after HWBIST execution) so RTOSINT information is not lost. 1. Disable RTOSINT: Set ERAD_COUNTER_REGS.CTM_CNTL.RTOSINT = 0 if the Counter module is configured to generate RTOSINT or Set ERAD_COUNTER_REGS.HWBP_CNTL.RTOSINT = 0 if the HWBP module is configured to generate RTOSINT HWBIST context save HWBIST context restore Check the STATUS registers for any ERAD events that occurred during HWBIST execution and take the appropriate action: Set ERAD_COUNTER_REGS.CTM_STATUS.EVENT_FIRED = 1 to check for any CTM events or Set ERAD_COUNTER_REGS.HWBP_STATUS.EVENT_FIRED = 1 to check for any HWBP events Enable RTOSINT: Set ERAD_COUNTER_REGS.CTM_CNTL.RTOSINT = 1 if the Counter module is configured to generate RTOSINT or Set ERAD_COUNTER_REGS.HWBP_CNTL.RTOSINT = 1 if the HWBP module is configured to generate RTOSINT or

Advisory	I2C: Target Transmitter Mode, Standard Mode SDA Timings Limitation											
Revision Affected	0, A	N .										
Details		e I2C peripher _ (Clock) line	clock-stretch the									
	There is a requirement from the I2C Specification for a Fast-mode device used in Standard-mode system to meet $t_{SU:DAT}$ (data set-up time) + $t_{r(max)}$ (rise time) beforeleasing the SCL line. See Footnote 4 of the "Characteristics of the SDA and SC bus lines for Standard, Fast, and Fast-mode Plus I ² C-bus devices" table in the NX Semiconductors <i>I</i> ² C-bus specification and user manual (UM10204).											
	However, the C2000 I2C clock-stretches the SCL line by a fixed amount = 6 * f _{mod} (I2C Clock rate of the C2000) in the above scenario. When the C2000 [™] microcont acting as a target transmitter with a Standard-mode host, it is possible for the clock (SCL) to be released by the C2000 before the data (SDA) is ready, if the t _r of SDA long.											
	The "Pull-up resistor sizing" section in the NXP Semiconductors I^2C -bus specification and user manual (UM10204) gives more details on choosing the appropriate PU resistor (R_p), based on the rise time (t_r) and bus capacitance (C_b) shown in Equation 1.											
		$R_{p(max)} =$	$=\frac{t_r}{0.8473\times C_b}$			(1)						
Workaround	 Reducing t_r with a strong pullup In order to ensure that t_{SU:DAT} + t_{r(max)} is met, the user can configure the pullup resistance on the SDA line such that it meets the constraints listed in the SDA D Rise Time Requirement column of Table 3-1 based on the value of f_{mod} Clock in system. This will ensure that the data present on the SDA line is valid when the C2000 releases the SCL signal. 											
Table 3-2 gives suggested R_p resistor values for a given f_{mod} Clock (MHz) and (capacitance). For other values of C_b , please use Equation 1 to calculate the va R_p needed in the system.												
		Table 3-1.	Data Rise Time F	Requirements fo Standard-Mode		et Transmitter with						
				SCL Clock-	Data Set-up							

f _{mod} Clock (MHz)	f _{mod} Period (ns)	SCL Clock- Stretch Delay from C2000 I2C (ns): (6*f _{mod} Clock)	Data Set-up Time (ns): t _{SU:DAT} (Standard Mode)	SDA Data Rise Time Requirement (ns): t _r
7	142.9	857		607
8	125	750		500
9	111	666	250	416
10	100	600	230	350
11	90.9	545		295
12	83.3	500		250



Advisory (continued) I2C: Target Transmitter Mode, Standard Mode SDA Timings Limitation

Table 3-2. Pullup Resistor (R _p) Values for Common Bus Capacitances (C _b)					
f _{mod} Clock (MHz)	SDA Data Rise Time Requirement (ns): t _r	R _p (kΩ) for C _b = 100 pF	R _p (kΩ) for C _b = 200 pF	R _p (kΩ) for C _b = 300 pF	R _p (kΩ) for C _b = 400 pF
7	607	7.1	3.5	2.3	1.7
8	500	5.9	2.9	1.9	1.4
9	416	4.9	2.4	1.6	1.2
10	350	4.1	2.0	1.3	1.0
11	295	3.4	1.7	1.1	0.8
12	250	2.9	1.4	0.9	0.7

2. t_r = 1000 ns

This workaround is not preferred due to restrictions in general I2C usage, use Workaround 1 when possible.

If the system is such that it requires 1000 ns of rise time on the SDA line, the C2000 I2C f_{mod} Clock can be configured to 4.8 MHz so the clock-stretching (6 * f_{mod} Clock) satisfies this requirement. This results in $t_r = (1/4.8 \text{ MHz}) * 6 = 1000 \text{ ns}$. This workaround is only valid in systems where the C2000 I2C is the target on the I2C bus. Note that 4.8 MHz is outside the data sheet's required range of 7 MHz to 12 MHz for f_{mod} Clock. Using f_{mod} at 4.8 MHz, even though it is outside of the data sheet's required range, will work for the C2000 I2C in Target mode on a Standard-mode host bus. Using $f_{mod} = 4.8$ MHz in any other configurations except the one listed in this workaround will cause other timing parameters to be violated and is not allowed.

Advisory	MCD: Missing Clock Detect Should be Disabled When the PLL is Enabled (PLLCLKEN = 1)
Revisions Affected	0, A
Details	The PLL has a limp mode feature to provide a slow PLLRAWCLK output even if its input OSCCLK is absent. Independently, the Missing Clock Detect (MCD) circuit will forcibly switch the system clock source to INTOSC1 when a missing OSCCLK input is detected. The MCD mux to switch between these system clock sources is not ensured to be glitch-free when both clock sources (PLLRAWCLK and INTOSC1) are still active. In rare cases, this may lead to unpredictable device behavior during a missing clock failure event.
Workarounds	When the PLL is used by the system (PLLCLKEN = 1), disable the MCD by writing MCDCR.MCLKOFF = 1.
	The Dual Clock Comparator (DCC) circuit can be configured to quickly detect if the SYSCLK frequency drops outside the desired frequency to its limp mode due to a missing clock event.
	When the system is operating in PLL bypass mode (PLLCLKEN = 0), the MCD circuit can still be used to detect missing clock events and switch the clock source to INTOSC1.



Advisory	Memory: Prefetching Beyond Valid Memory			
Revisions Affected	0, A			
Details			tions beyond those currently active in its pipel of valid memory, then the CPU may receive ar	
Workarounds	M1, GS15 – The prefetch queue is 8 x16 words in depth. Therefore, code should not come within 8 words of the end of valid memory. Prefetching across the boundary between two valid memory blocks is all right.			
	Example 1: M1 ends at address 0x7FF and is not followed by another memory block. Code in M1 should be stored no farther than address 0x7F7. Addresses 0x7F8–0x7FF should not be used for code.			
	Example 2: M0 ends at address 0x3FF and valid memory (M1) follows it. Code in M0 can be stored up to and including address 0x3FF. Code can also cross into M1, up to and including address 0x7F7.			
	Flash – The prefetch queue is 16 x16 words in depth. Therefore, code should not come within 16 words of the end of valid memory; otherwise, it generates a Flash ECC uncorrectable error.			
	Table 3-3. Memories Impacted by Advisory			
		MEMORY TYPE	ADDRESSES IMPACTED	
		M1	0x0000 07F8-0x0000 07FF	
		GS15	0x0001 CFF8-0x0001 CFFF	
		Flash	0x000B FFF0-0x000B FFFF	

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Advisory	SDFM: Dynamically Changing Threshold Settings (LLT, HLT), Filter Type, or COSR Settings Will Trigger Spurious Comparator Events
Revisions Affected	0, A
Details	When SDFM comparator settings—such as filter type, lower/upper threshold, or comparator OSR (COSR) settings—are dynamically changed during run time, spurious comparator events will be triggered. The spurious comparator event will trigger a corresponding CPU interrupt, CLA task, ePWM X-BAR events, and GPIO output X-BAR events if configured appropriately.
Workaround	 When comparator settings need to be changed dynamically, follow the procedure below to ensure spurious comparator events do not generate a CPU interrupt, CLA task, or X-BAR events (ePWM X-BAR/GPIO output X-BAR events): 1. Disable the comparator filter. 2. Delay for at least a latency of the comparator filter + 3 SD-Cx clock cycles. 3. Change comparator filter settings such as filter type, COSR, or lower/upper threshold. 4. Delay for at least a latency of the comparator filter + 5 SD-Cx clock cycles. 5. Enable the comparator filter.
Advisory	SDFM: Dynamically Changing Data Filter Settings (Such as Filter Type or DOSR) Will Trigger Spurious Data Acknowledge Events
Revisions Affected	0, A
Details	When SDFM data settings—such as filter type or DOSR settings—are dynamically changed during run time, spurious data-filter-ready events will be triggered. The spurious data-ready event will trigger a corresponding CPU interrupt, CLA task, and DMA trigger if configured appropriately.
Workaround	 When SDFM data filter settings need to be changed dynamically, follow the procedure below to ensure spurious data-filter-ready events are not generated: Disable the data filter. Delay for at least a latency of the data filter + 3 SD-Cx clock cycles. Change data filter settings such as filter type and DOSR. Delay for at least a latency of the data filter + 5 SD-Cx clock cycles. Enable the data filter.



Advisory	SDFM: Two Back-to-Back Writes to SDCPARMx Register Bit Fields CEVT1SEL, CEVT2SEL, and HZEN Within Three SD-Modulator Clock Cycles can Corrupt SDFM State Machine, Resulting in Spurious Comparator Events
Revisions Affected	0, A
Details	Back-to-back writes to SDCPARMx register bit fields CEVT1SEL, CEVT2SEL, and HZEN within three SD-modulator clock cycles can potentially corrupt the SDFM state machine, resulting in spurious comparator events, which can potentially trigger CPU interrupts, CLA tasks, ePWM XBAR events, and GPIO output X-BAR events if configured appropriately.
Workaround	Avoid back-to-back writes within three SD-modulator clock cycles or have the SDCPARMx register bit fields configured in one register write.

Advisory	SYSTEM: Multiple Successive Writes to CLKSRCCTL1 Can Cause a System Hang		
Revisions Affected	0, A		
Details When the CLKSRCCTL1 register is written more than once without delay be the system can hang and can only be recovered by an external XRSn resereset. The occurrence of this condition depends on the clock ratio between the clock selected by OSCCLKSRCSEL, and may not occur every time. If this issue is encountered while using the debugger, then after hitting paus counter will be at the Boot ROM reset vector.		an external XRSn reset or Watchdog ne clock ratio between SYSCLK and	
		, then after hitting pause, the program	
	Implementing the workaround will avoid this condition	n for any SYSCLK to OSCCLK ratio.	
Workaround Add a software delay of 300 SYSCLK cycles using an NOP instruction afte the CLKSRCCTL1 register. Example:		n NOP instruction after every write to	
	<pre>' ' ClkCfgRegs.CLKSRCCTL1.bit.INTOSC20FF=0; asm(" RPT #250 NOP"); asm(" RPT #50 NOP"); ClkCfgRegs.CLKSRCCTL1.bit.OSCCLKSRCSEL = 0; asm(" RPT #250 NOP"); asm(" RPT #50 NOP");</pre>	<pre>// Turn on INTOSC2 // Delay of 250 SYSCLK Cycles // Delay of 50 SYSCLK Cycles // Clk Src = INTOSC2 // Delay of 250 SYSCLK Cycles // Delay of 50 SYSCLK Cycles</pre>	

C2000Ware_3_00_00_00 and later revisions will have this workaround implemented.



Advisory	USB: USB DMA Event Triggers are not Supported
Revisions Affected	0, A
Details	The USB module generates inadvertent extra DMA requests, causing the FIFO to overflow (on IN endpoints) or underflow (on OUT endpoints). This causes invalid IN DATA packets (larger than the maximum packet size) and duplicate receive data.
Workaround	None

Advisory	Watchdog: WDKEY Register is not EALLOW-Protected
Revisions Affected	0, A
Details	The WDKEY register is not EALLOW-protected. Issuing the EALLOW and EDIS instructions to write to this register is not required. To enable software reuse on other devices where WDKEY is EALLOW-protected, using EALLOW and EDIS is recommended.
Workaround	None



4 Silicon Revision 0 Usage Notes and Advisories

This section lists the usage notes and advisories for this silicon revision.

4.1 Silicon Revision 0 Usage Notes

Silicon revision-applicable usage notes have been found on a later silicon revision. For more details, see Silicon Revision A Usage Notes.

4.2 Silicon Revision 0 Advisories

Silicon revision-applicable advisories have been found on a later silicon revision. For more details, see Silicon Revision A Advisories.

Advisory	ADC: External SOC Trigger (ADCEXTSOC) Cannot be Used to Trigger Multiple ADCs
Revision Affected	0
Details	When multiple ADCs are to be used in parallel (for simultaneous sampling), the ADCs should use the same trigger source to ensure all ADCs start synchronously for best ADC performance.
	The external SOC trigger source (ADCEXTSOC) from the Input-XBAR may not trigger all ADCs simultaneously due to internal timing skew from the XBAR to each ADC.
Workaround	 Use an alternate trigger source when multiple simultaneous ADC conversions are required. Only use ADCEXTSOC to trigger a single ADC. Account for the reduced ADC performance when using ADCEXTSOC to trigger multiple ADCs for ADC modes that specify reduced performance for asynchronous operation.

Advisory	ePWM: Event Latch (DCxEVTxLAT) of "DC Event-Based CBC Trip" May not Extend Trigger Pulse as Expected When Asynchronous Path is Selected
Revision Affected	0
Details	DCxEVTxLAT may lose the captured trigger event for an asynchronous input upon deassertion. When an asynchronous trigger is deasserted, it is expected that the flop holds the value until there is a Clear event. Since the trigger is asynchronous with respect to the clock of the flop, there is a possibility that the flop may get cleared during deassertion. This would result in a loss of event latch function.
Workaround	None



Advisory	ESC: EtherCAT Slave Controller Distributed Clocking (DC) Mode is not Supported
Revision Affected	0
Details	The EtherCAT Slave Controller Distributed Clocking registers responsible for offset and drift compensation are only writable by the host CPU and not by the EtherCAT master. Because of this, Distributed Clocking Mode is not supported on the affected revision.
Workaround	None
Advisory	ESC: EtherCAT Slave Controller may not Work with a Non-Gigabit PHY
Revision Affected	0
Details	The EtherCAT Slave Controller configures the PHY registers assuming it is gigabit- capable. This may result in undesirable PHY operation if a non-gigabit PHY is used.
Workaround	Use a gigabit PHY.
Advisory	ESC: The CPU1 DMA Access is Only Available to the Lower 4KB of the ESC RAM Memory Map
Revision Affected	0
Details	The CPU1 DMA access is only available to the lower 4KB of the ESC RAM memory map. This memory region is 0x52000 to 0x527FF.
Workaround	None

Advisory	Ethernet: Incorrect Flexible Pulse-per-Second (PPS) Output Interval When Fine Correction Method is Used
Revision Affected	0
Details	The Ethernet module provides two programmable options—fine and coarse—for correcting the IEEE 1588 internal time reference. When the coarse correction method is used, the correction is applied in one shot and does not affect the flexible PPS output. When the fine correction method is used, the correction is applied uniformly and continuously to the IEEE 1588 internal time reference as well as to the flexible PPS output. However, due to this defect, when fine correction method is used and the drift in the frequency of the clock that drives the IEEE 1588 internal time reference is large (when compared with the grandmaster source clock), the flexible PPS output interval is incorrect. This does not impact the IEEE 1588 internal time reference updates.
	The internal PPS counter used for generating the PPS interval is incorrectly reset earlier than expected, resulting in the next PPS cycle starting incorrectly, earlier than expected. The incorrect Flexible PPS Output Interval from the Ethernet module can cause external devices that are synchronized with the flexible PPS trigger outputs to go out of synchronization.
Workaround	The application can use the coarse method for correcting the IEEE 1588 internal time reference. Because the time correction is applied in a single shot in the coarse correction method, timestamp captured for, at the most, one packet is impacted.
Advisory	Ethernet: False Dribble and CRC Error Reported in RMII 10Mbps Mode for a Specific Phase Relation Between MAC Receiver Clock and Assertion of RMII CRS_DV Input
Revision Affected	0
Details	If the MAC is operating in the RMII 10Mbps speed mode and the RMII CRS_DV is asserted two RMII clock rising edges ahead of data, the Ethernet module reports a false dribble and a CRC error in the Receive status. The dribble error is reported when the Ethernet module receives an odd number of nibbles (4-bit words) and a CRC error is additionally reported. There is no data loss or corruption of packets forwarded to the software. However, if the error-packet drop is enabled (FEP bit in MTL_RxQ(#i)_Operation_Mode register is set to 0), the Ethernet module drops the packets, causing packet loss and impacting performance. If the error-packet drop is disabled (FEP bit in MTL_RxQ(#i)_Operation_Mode register is set to 1), the Ethernet module forwards the packet to the software, up to the byte boundary, and there is no data loss or corruption.
Workaround	If the error-packet drop is enabled (FEP bit in MTL_RxQ(#i)_Operation_Mode register is set to 0), software can disable it and take the dropping decision based on the Rx status. If the error-packet drop is disabled (FEP bit in MTL_RxQ(#i)_Operation_Mode register is set to 1), software can ignore the dribble and CRC error and accept packets that have both these errors together. The occurrence of real dribble error is rare and happens when there are synchronization issues due to faulty clock recovery.



Advisory	FSI: RX FIFO Spurious Overrun
Revision Affected	0
Details	A buffer overrun is asserted when the last location of the FIFO is written.
Workarounds	 Two possible workarounds are available. 1. Set up the communication between the transmitting and receiving modules in such a way that the maximum number of data words received, before the first data word is read, is 15 (not 16). Under this condition, buffer overrun behavior is reliable. 2. If the application must fill all 16 data words in the receive buffer before the first data word is read (NWORD packet with 16 words), then the following sequence can be used: Ignore RX buffer overrun RX_EVT_STS.BUF_OVERRUN. On RX_EVT_STS.FRAME_DONE, read RX_BUF_PTR_STS.CURR_WORD_CNT and check that it is 16. Use DMA or software to move the data out of the RX buffer. Read RX_BUF_PTR_STS.CURR_WORD_CNT and check that it is 0. Clear the RX_EVT_STS.FRAME_DONE. Flag by writing a 1 to RX_EVT_CLR.FRAME_DONE.

Advisory	INTOSC: VDDOSC Powered Without VDD can Cause INTOSC Frequency Drift
Revision Affected	0
Details	If VDDOSC is powered on while VDD is not powered, there will be an accumulating and persistent downward frequency drift for INTOSC1 and INTOSC2. The rate of drift accumulated will be greater when VDDOSC is powered without VDD at high temperatures.
	As a result of this drift, the INTOSC1 and INTOSC2 internal oscillator frequencies could fall below the minimum values specified in the <i>TMS320F2838x Real-Time Microcontrollers With Connectivity Manager</i> data sheet. This would impact applications using INTOSC2 as the clock source for the PLL, with the system operating at a lower frequency than expected.
Workaround	 Keep VDDOSC and VDD powered together. Use the external X1 and X2 crystal oscillators as the PLL clock source. The crystal oscillator does not have any drift related to VDDOSC and VDD supply sequencing.



Advisory Revision Affected	MPOST: Memory Power-on-Self-Test will not Work at Full Speed
Details	Memory Power-on-Self-Test (MPOST) may fail with any clock option except PLL bypass.
Workaround	If using MPOST, use only PLL bypass option (GPREG2[7:4] = 0×9).

Advisory	Reset: Elevated VDD Current During Reset
Revision Affected	0
Details	There is an elevated current of approximately 70 mA for each C28x CPU while held in reset. When the XRSn pin is low, both C28x cores will be in reset, resulting in 140 mA of additional current. After XRSn is released, there will be approximately 70 mA of current from the C28x CPU2 until it is released by from reset by CPU1.
Workaround	Do not hold XRSn low or keep CPU2 in reset for extended durations when current consumption is a concern.



5 Documentation Support

For device-specific data sheets and related documentation, visit the TI web site at: https://www.ti.com.

For more information regarding the TMS320F2838x devices, see the following documents:

- TMS320F2838x Real-Time Microcontrollers With Connectivity Manager data sheet
- TMS320F2838x Real-Time Microcontrollers Technical Reference Manual

6 Trademarks

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7 Revision History

Changes from September 3, 2022 to February 21, 2024 (from Revision E (September 2022) to Revision F (February 2024))

R	Revision F (February 2024))		
•	Added Security: The primary layer of defense is securing the boundary of the chip, which begins with		
	enabling JTAGLOCK and Zero-pin Boot to Flash feature Usage Note	7	
•	Added HWBIST: Avoiding Spurious Interrupts While Using HWBIST advisory	19	
•	Added HWBIST: No Cross-Triggering From One CPU While One of the C28x Cores is Going Through		
	HWBIST Check advisory.	19	
•	Added HWBIST: RTOSINT Interrupt Asserted During HWBIST Run Does Not Get Logged advisory		
•	Added I2C: Target Transmitter Mode, Standard Mode SDA Timings Limitation advisory	21	

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